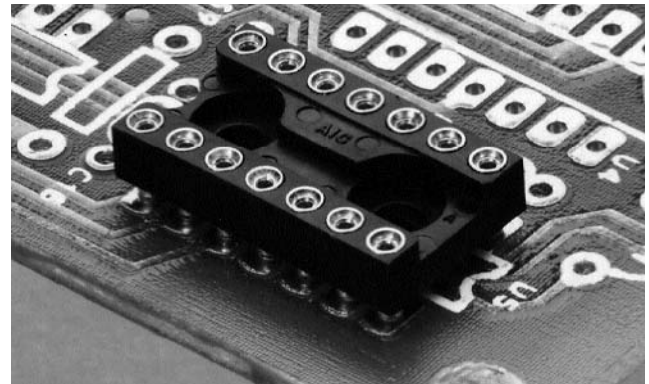
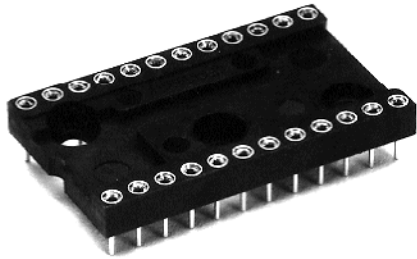


Standard & High Temperature Closed Frame DIP Sockets

Conforms to NECQ/EIA 540D000 & 540DAAA Standards



Features:

- Multiple finger contact on all sockets assures maximum reliability.
- Tapered entry for ease of insertion.
- Closed bottom sleeve for 100% anti-wicking of solder.
- To fit .100" (2.54 mm) pitch.
- Easily customized to fit your application.
- For surface mount applications use HDS only.

Terminals and Contacts:

Terminal: Brass - Copper Alloy (C36000) ASTM-B-16

Contact: Beryllium Copper - Copper Alloy (C17200) ASTM-B-194

Solder Preform:

63% Tin, 37% Lead

Plating:

Terminal: Gold over Nickel or Tin-Lead over Nickel

Contact: Gold over Nickel or Tin-Lead over Nickel

Gold per MIL-G-45204

Tin-Lead per MIL-P-81728

Nickel per QQ-N-290

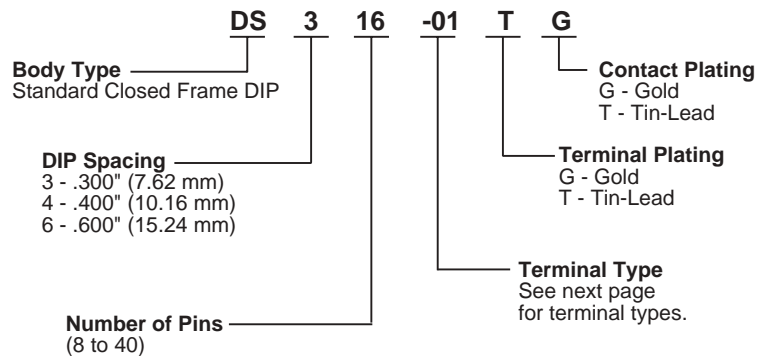
Standard Sockets

DS - Insulator Material:

Glass Filled Thermoplastic Polyester (P.B.T.)

U.L. Rated 94V-O, -60°C to 140°C (-76°F to 284°F)

How To Order



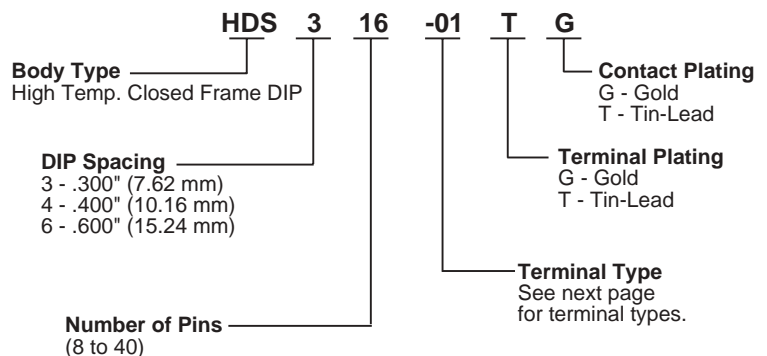
High Temperature Sockets

HDS - Insulator Material:

High Temp. Glass Filled Thermoplastic

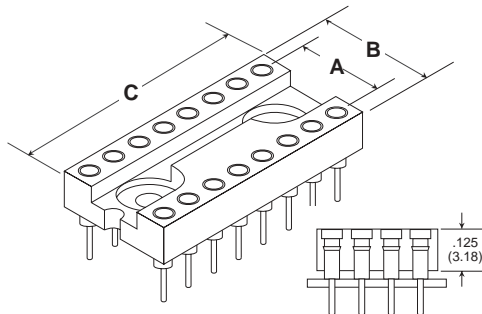
U.L. Rated 94V-O, -60°C to 260°C (-76°F to 500°F)

How To Order



Standard & High Temperature Closed Frame DIP Sockets

Conforms to NECQ/EIA 540D000 & 540DAAA Standards



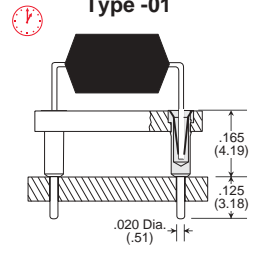
Dimensional Information

# of Pins	A	B	C
8	.300 (7.62)	.400 (10.16)	.400 (10.16)
14	.300 (7.62)	.400 (10.16)	.700 (17.78)
16	.300 (7.62)	.400 (10.16)	.800 (20.32)
18	.300 (7.62)	.400 (10.16)	.900 (22.86)
20	.300 (7.62)	.400 (10.16)	1.000 (25.40)
22	.400 (10.16)	.500 (12.70)	1.100 (27.94)
24	.600 (15.24)	.700 (17.78)	1.200 (30.48)
28	.600 (15.24)	.700 (17.78)	1.400 (35.56)
40	.600 (15.24)	.700 (17.78)	2.000 (50.80)

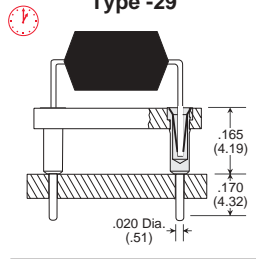
Also available in Open Frame,
LS series, see page 82

Terminal Information

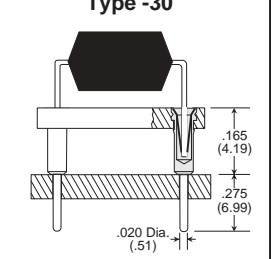
Low Profile Solder Tail
Type -01



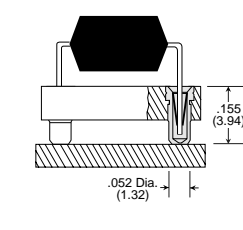
Low Profile Solder Tail
Type -29



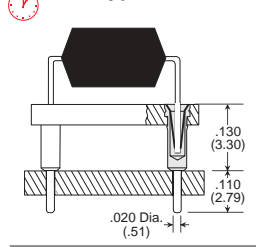
Low Profile Solder Tail
Type -30



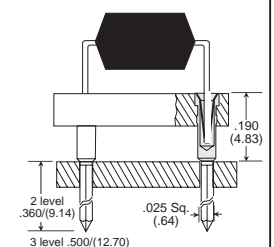
Surface Mount
Type -37
HDS Only



Low Profile Solder Tail
Type -51



Wire Wrap®
Type -02,-03



Quick turn delivery available on standard terminal types.

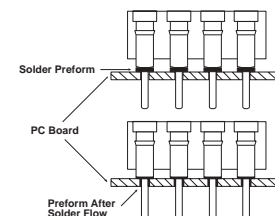
Additional terminal types available.
See terminal section for detailed terminal information.

Solder Preform PGA Sockets - Intrusive Reflow Application

Available on HDS Body Type

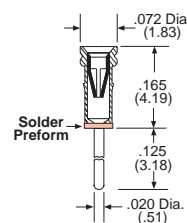
Features:

- Combines the labor of socket loading and solder application into one operation.
- Eliminates the use of solder paste and screening operation.
- Eliminates solder bridges and/or solder shorts due to excess solder.
- Ensures a reliable solder joint with controlled solder volume.
- Ideal for surface mount and mixed technology applications.
- For custom solder preform terminal applications consult factory.
- See previous page for material specifications and how to order



Solder Preform Terminals

Type -150



Type -151

